

Product Texts

Base Polymer	Polypropylene Homopolymer
Special Features	laser etchable (dark etching)
Market Segment	various, electrical and electronic
Typical Applications	various

Processing/Physical Characteristics

	Value	Unit	Test Standard
ISO Data			
^[C] Melt volume-flow rate, MVR	7	cm ³ /10min	ISO 1133
Temperature	230	°C	-
Load	2.16	kg	-

[C]: CAMPUS

Mechanical properties

	Value	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	1400	MPa	ISO 527
^[C] Yield stress	32	MPa	ISO 527
^[C] Yield strain	9.9	%	ISO 527
^[C] Charpy impact strength, +23°C	130	kJ/m ²	ISO 179/1eU
^[C] Charpy notched impact strength, +23°C	5	kJ/m ²	ISO 179/1eA

[C]: CAMPUS

Thermal properties

	Value	Unit	Test Standard
ISO Data			
^[C] Temp. of deflection under load, 1.80 MPa	58	°C	ISO 75-1/-2
^[C] Vicat softening temperature, B	85	°C	ISO 306

[C]: CAMPUS

Other properties

	Value	Unit	Test Standard
^[C] Density	960	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics**Processing**

Injection Molding

Applications

Electrical and Electronical

Special Characteristics

Flame retardant

Regional Availability

North America, Europe, Asia Pacific, Near East/Africa

Features

Homopolymer

Other text information**Injection molding**

Pre-Drying Conditions in a dry air (dessiccant) dryer 2-3 °C
 for 80-120 h
 in an air circulating dryer 2-4 °C
 for 80-120 h

Processing Injection Moulding melt temperature 200-270 °C
 mould temperature 20-90 °C

Storage dry, protected from light